

Accepted Manuscript

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PII: S0032-3861(16)30163-X

DOI: [10.1016/j.polymer.2016.03.023](https://doi.org/10.1016/j.polymer.2016.03.023)

Reference: JPOL 18515

To appear in: *Polymer*

Received Date: 4 December 2015

Revised Date: 4 March 2016

Accepted Date: 7 March 2016

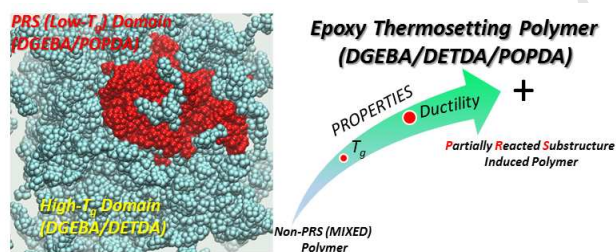
Please cite this article as: Jang C, Sharifi M, Palmese GR, Abrams CF, Toughness enhancement of thermosetting polymers using a novel partially reacted substructure curing protocol: A combined molecular simulation and experimental study, *Polymer* (2016), doi: 10.1016/j.polymer.2016.03.023.

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